

Fig. 1  
PRIOR ART

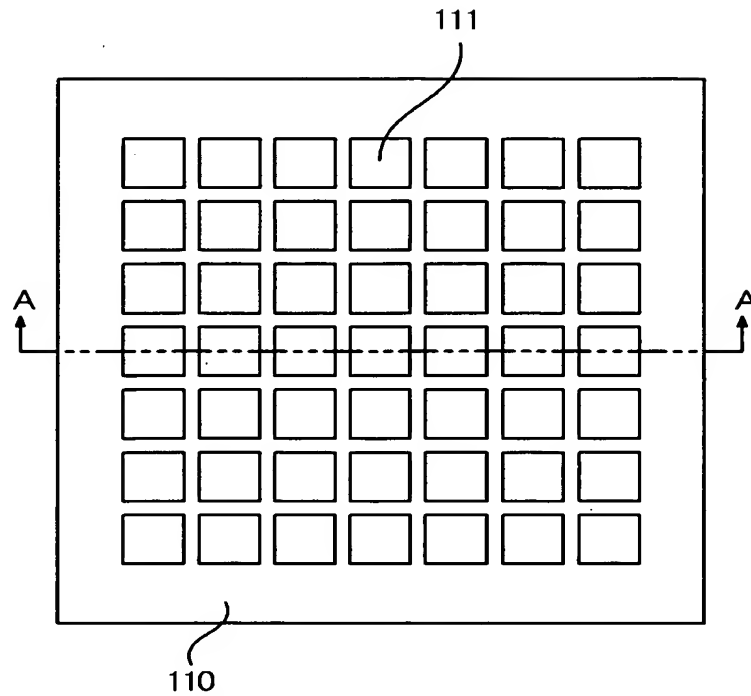
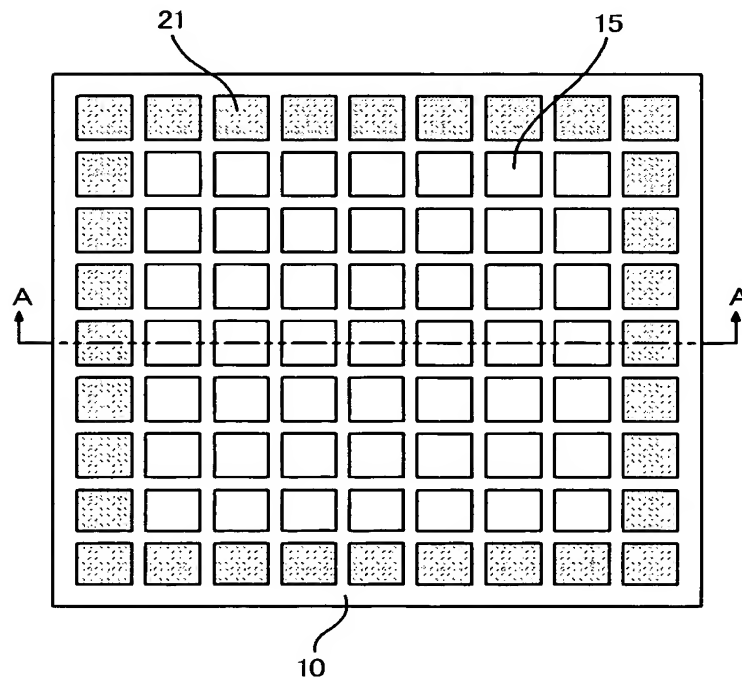


Fig. 3



Title: METHOD OF FABRICATING  
ELECTRONIC PARTS PACKAGED WITH  
RESIN AND BASEBOARD USED FOR THE  
METHOD  
Inventor: Shingo MASUKO  
Appln. No.: Unknown  
Docket No.: 025720-00023

Fig. 2 PRIOR ART

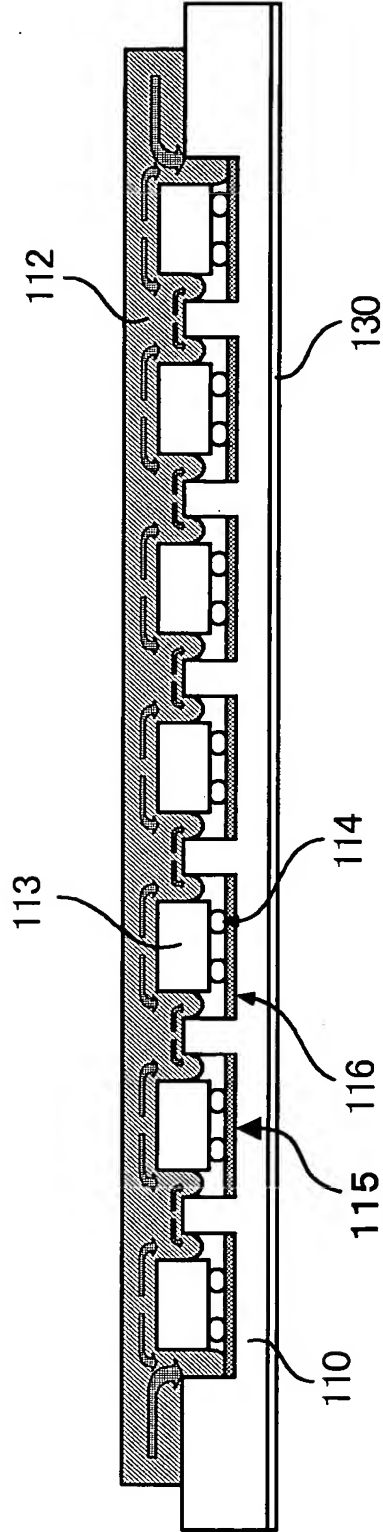


Fig. 4A

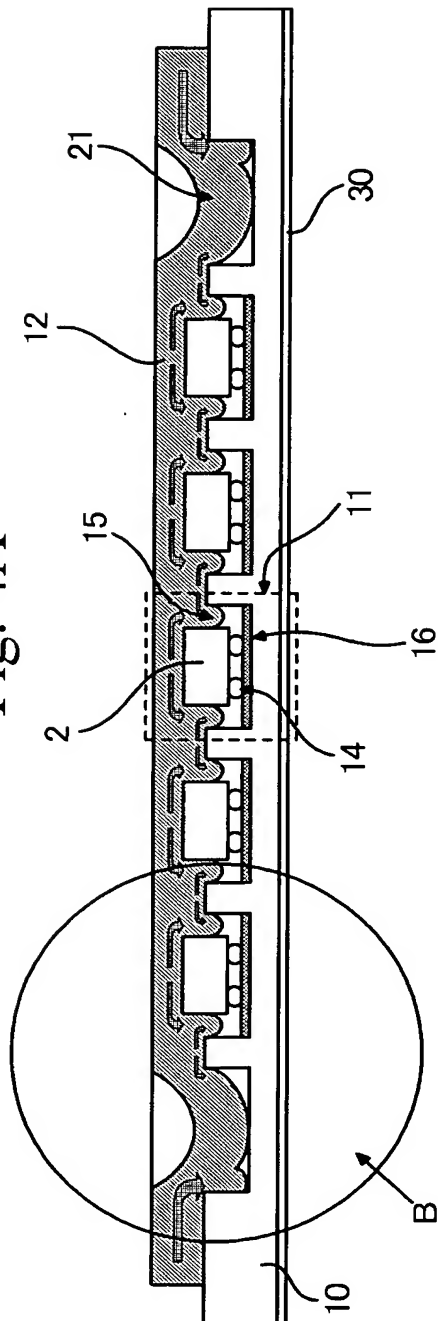


Fig. 4B

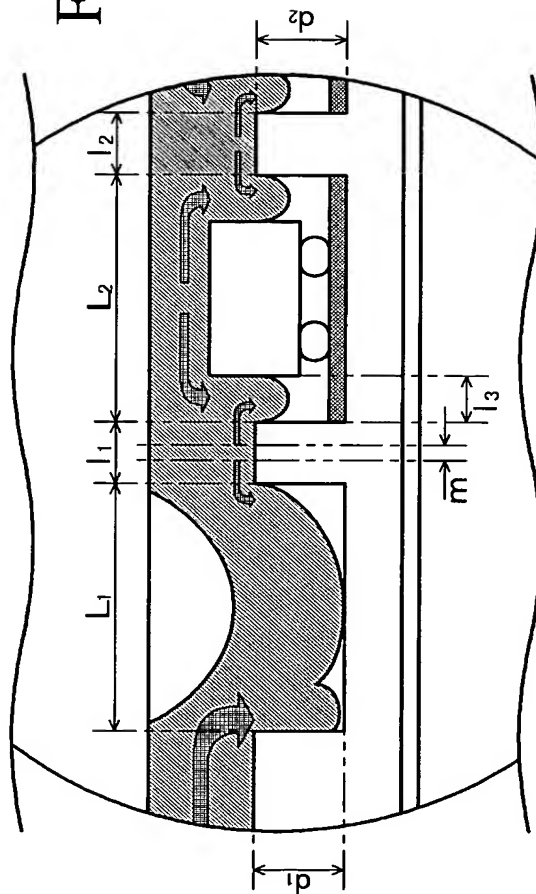


Fig. 5A



Fig. 5B

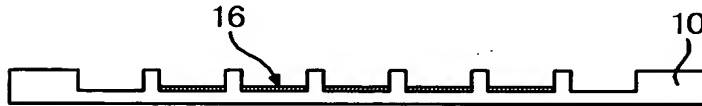


Fig. 5C

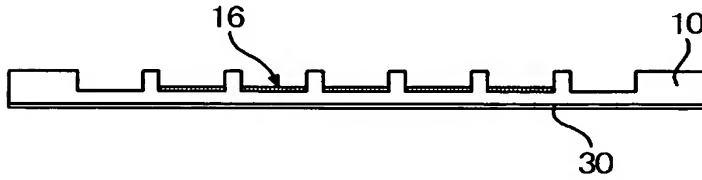


Fig. 5D

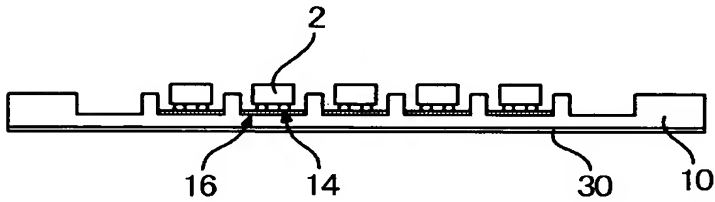


Fig. 5E

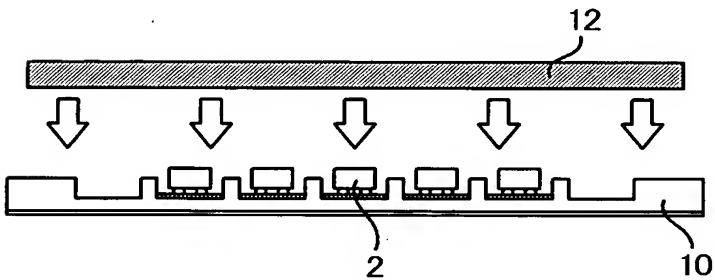


Fig. 5F

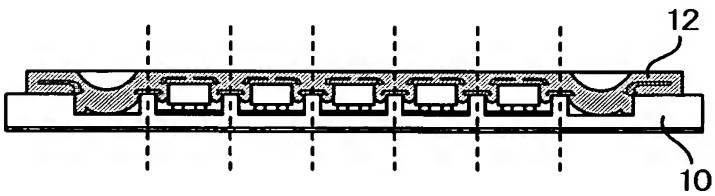


Fig. 5G



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Fig. 6

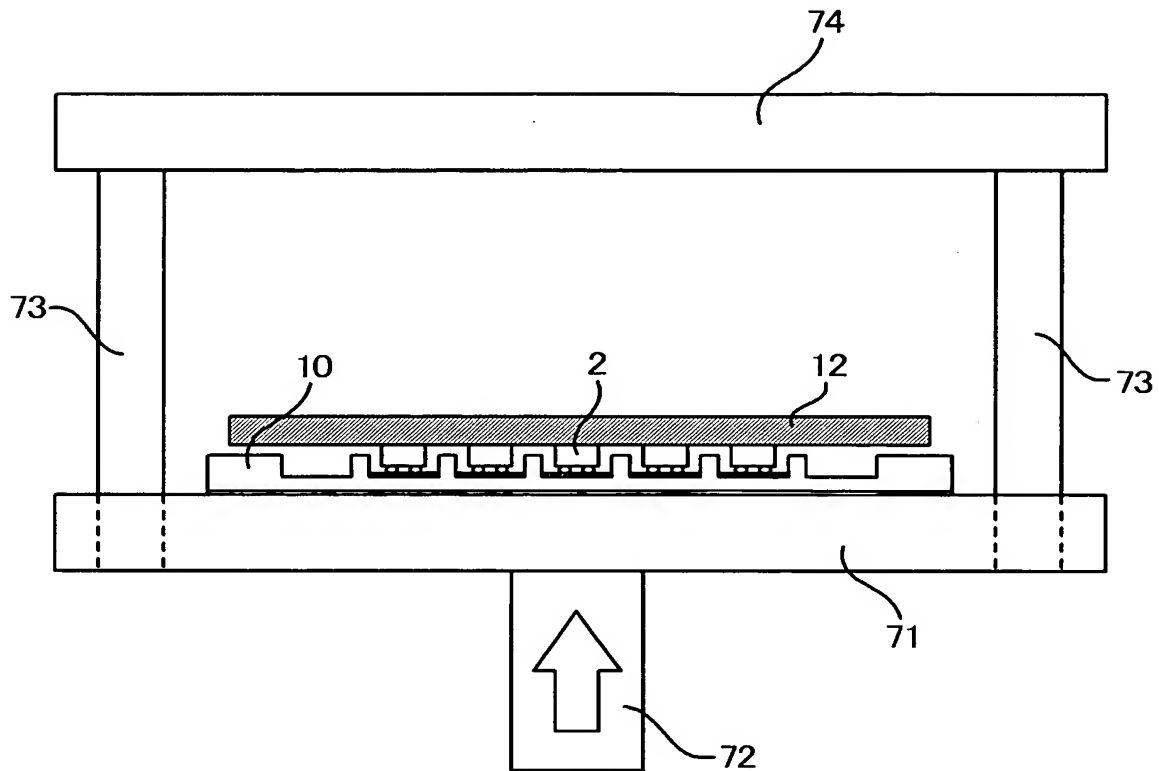


Fig. 7

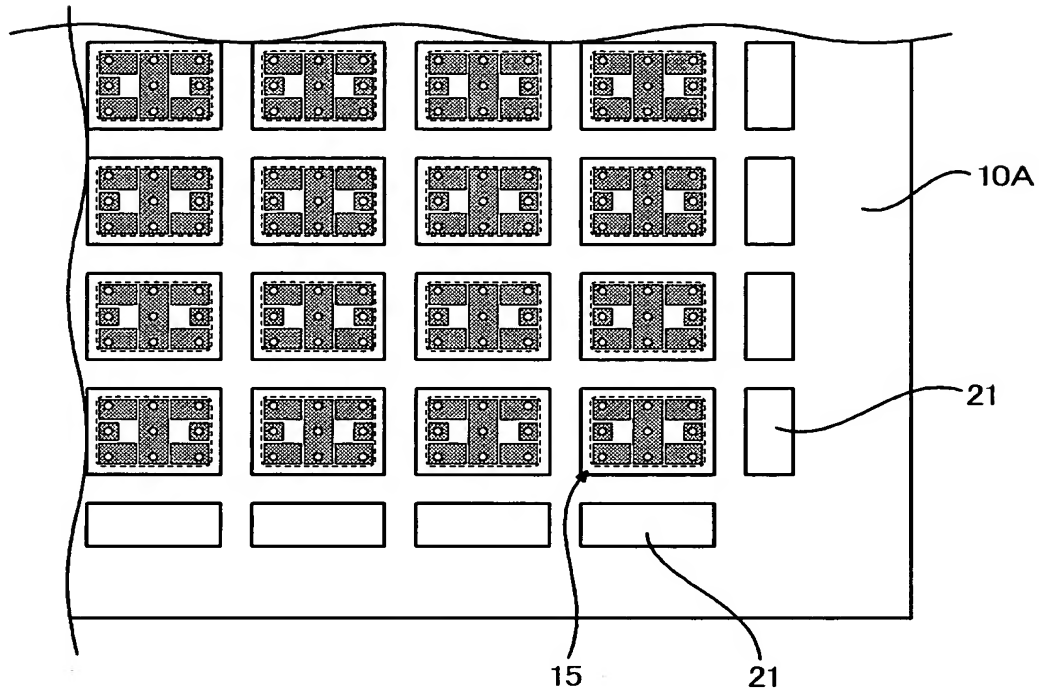
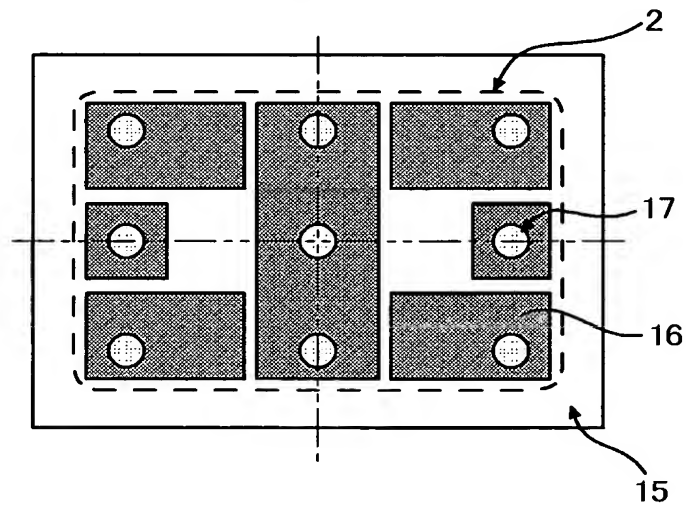


Fig. 8



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Fig. 9

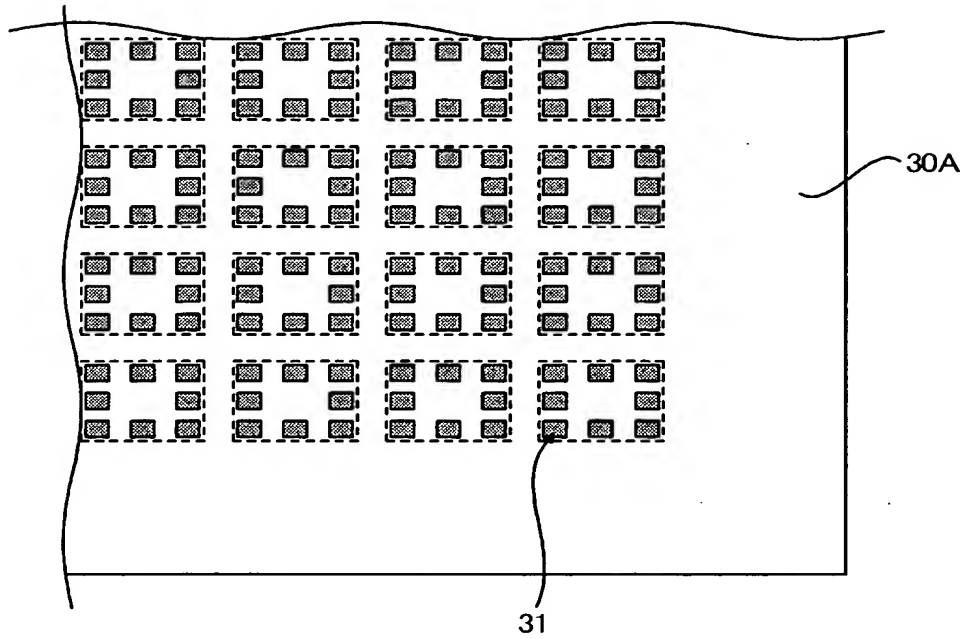
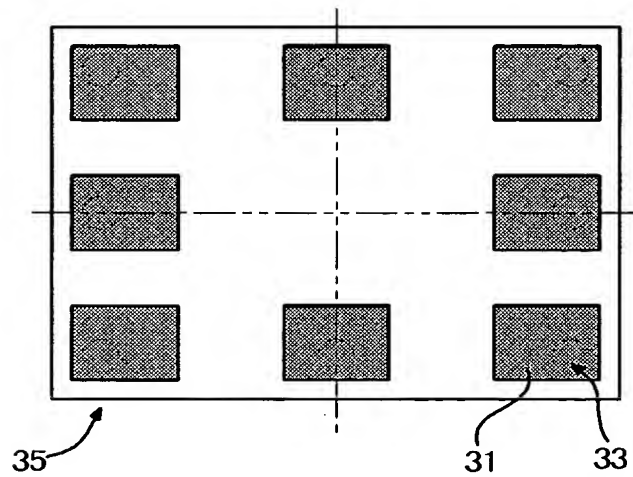


Fig. 10



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METHOD  
Inventor: Shingo MASUKO  
Appln. No.: Unknown  
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Fig. 11

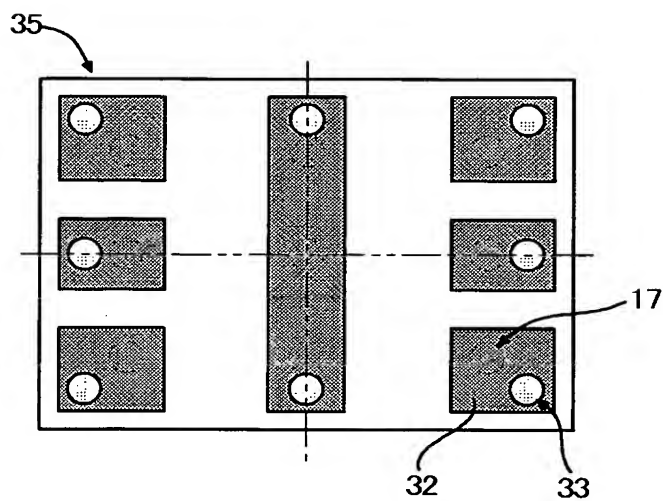


Fig. 12

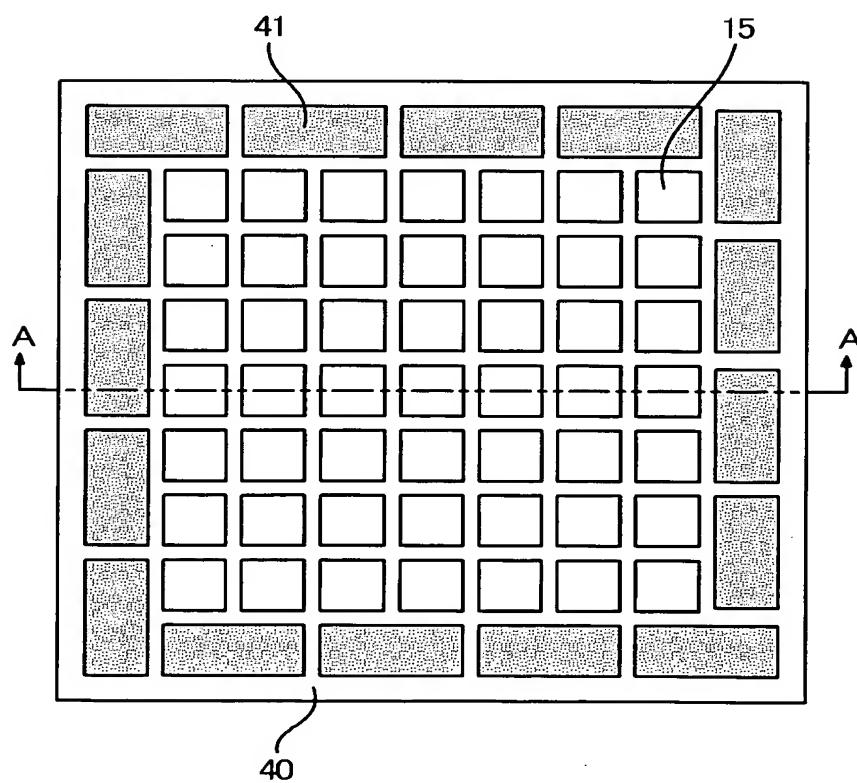




Fig. 13

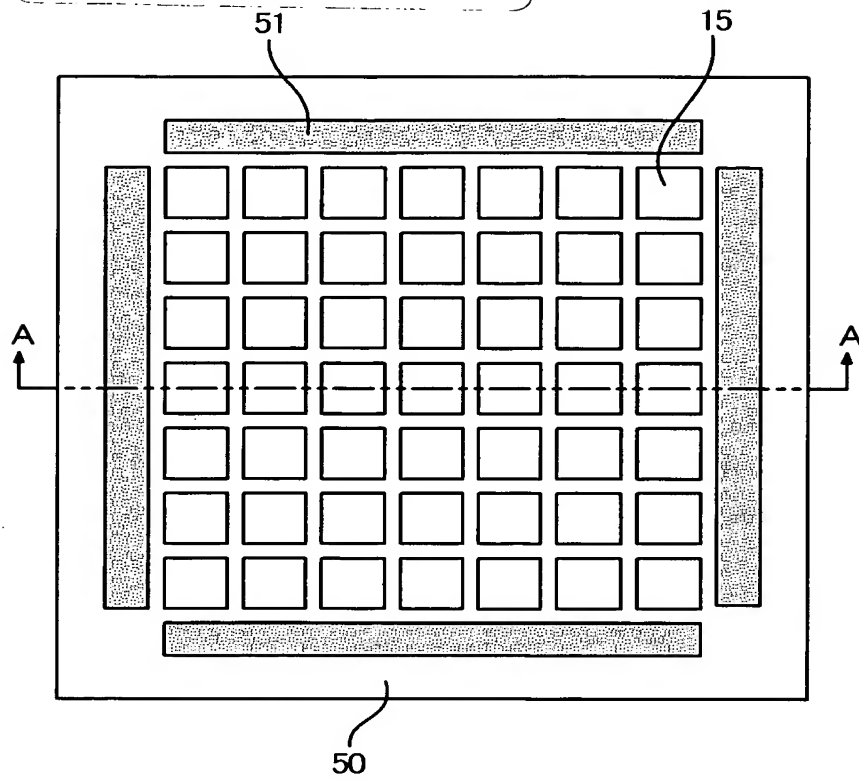


Fig. 14

